

BACK GRINDING WHEEL (RESIN & METAL)

• Technology

- Leading Technology in various types of machines and applications
- Wheel suitable for simultaneous grinding of multiple wafers
- Long life time and excellent bulk removal rate
- Providing proper wheel designs for various grinding methods and proper recipes

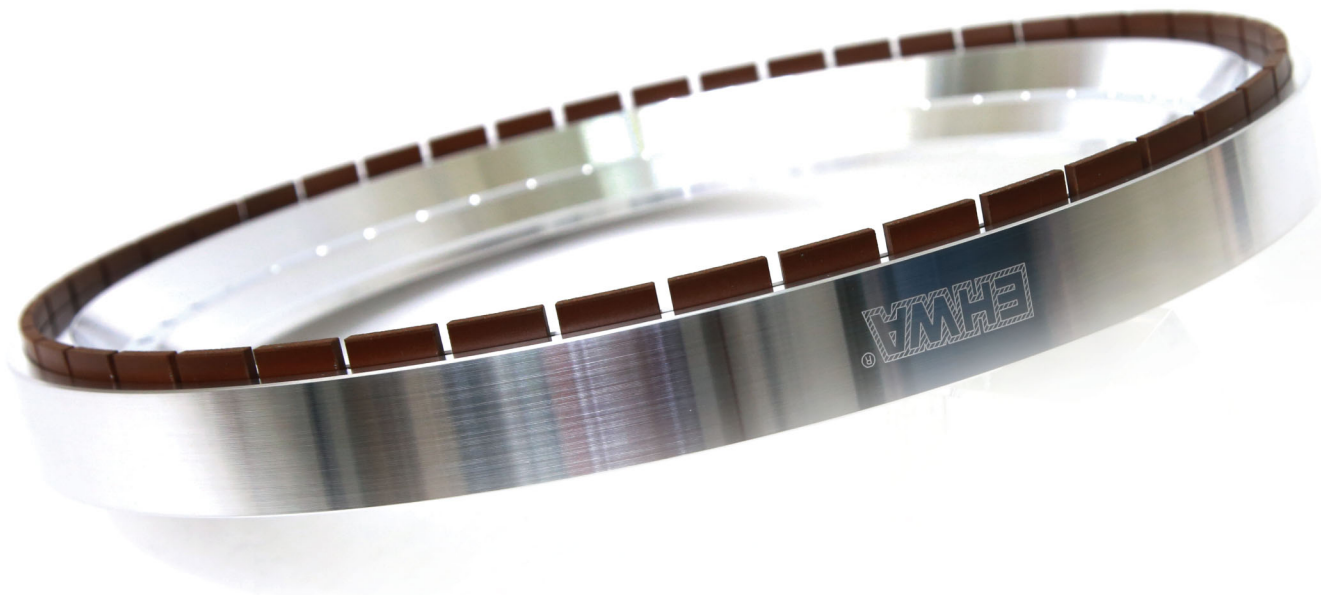
• Applications

- Silicon Wafer
- Sapphire Wafer
- SiC Wafer
- Glass Wafer
- High Hardness Material (Ex. Zirconia)

• Specifications

Process	Bond	D (mm)	W (mm)	X (mm)	Grit Size
Rough	RS, MS Series	200~380	2~5	3~10	#170~#800

Process	Bond	D (mm)	W (mm)	X (mm)	Grit Size
Fine	SW Series	200~380	2~5	3~10	#1200~#4000



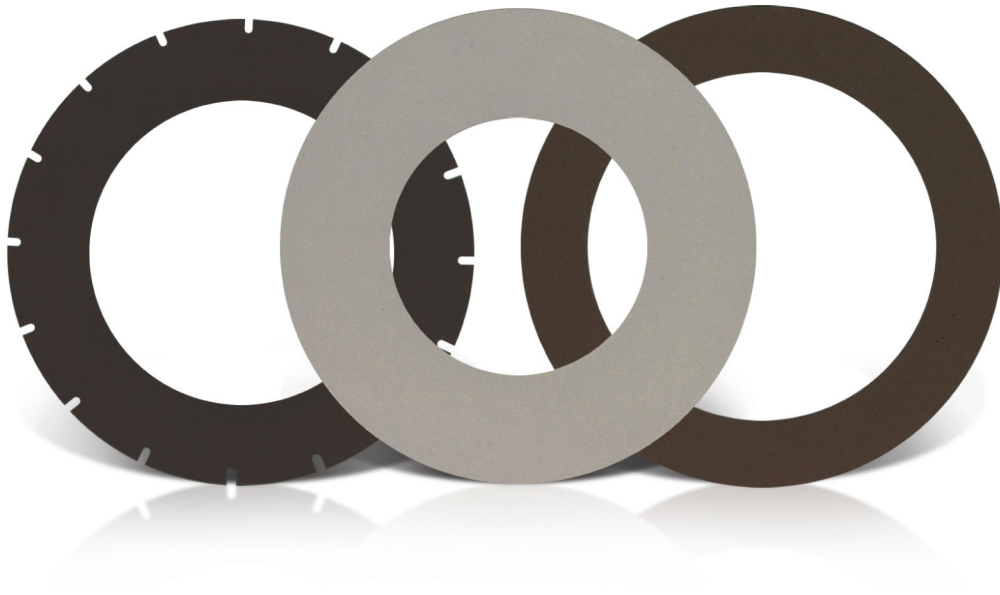
MICRO BLADE

• Advantages

- High precision thin blade with superior cutting efficiency
- Maintains free cutting action at high RPM and fast feed rates
- Eliminate chipping during the sawing operation

• Elements of Blade Structure

BNM Series	BS Series	BT Series	RB 15	MB 15	MF	MA	MB Series	MPQ2	MBA	MG4
Resin type			Metal type							
Hardness										
Glass / Quartz / Ceramic										
LTCC										
FBFA / CSP / LED										
QFN										
CABGA										
LED / MLF										
Electroforming type		Metal(Ni)		Hardness (Metal, Resin<)		Si, GaAs, amd PKG(Tape-CSP) cutting				



• EHWA New Blade

Conventional

Side enhancement

DICING BLADE



• Advantages

- High accuracy, super thin blade developed by EHWA
- Minimized chipping and superior consistency in quality through stringent particle
- Size distribution control
- Improve productivity by high feed speed
- Providing an optimized solution to the customers

• Si Wafer Dicing Mechanism

1. Wafer Top Side :
Wet cutting with coolant In general, fine diamond grit leads to small top side chipping.

2. Wafer Back Side :
Dry cutting without coolant In general, coarse diamond grit minimizes back size chipping due to its cutting ability and less load imposed on each grit.

Developing New Bond

- Application
Si and compound semiconductor
- Features
Small top and backside chipping
Improve productivity by high feed speed

